

B520C - B560C

#### **5.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER**

### **Features**

- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automated Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- Lead Free Finish/RoHS Compliant (Note 1)
- **Green Molding Compound (No Halogen and Antimony)** (Note 2)

## **Mechanical Data**

- Case: SMC
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.21 grams (approximate)







**Bottom View** 

## Maximum Ratings @TA = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	B520C	B530C	B540C	B550C	B560C	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	20	30	40	50	60	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	35	42	V
Average Rectified Output Current @ T <sub>T</sub> = 90°C	l <sub>0</sub>			5.0			Α
Non-Repetitive Peak Forward Surge Current, 8.3 ms Single Half-Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>			100			А

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Terminal	$R_{ hetaJT}$	10	°C/W
Thermal Resistance, Junction to Ambient (Note 2)	$R_{ heta JA}$	50	°C/W
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

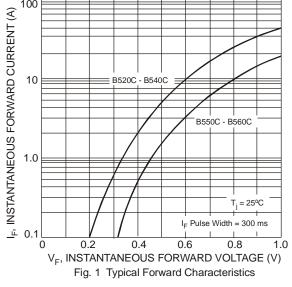
### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

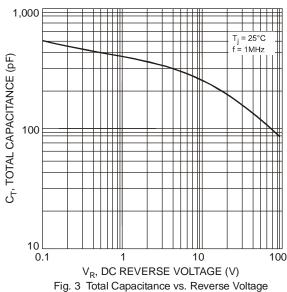
Charac	cteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	B520C, B530C, B540C B550C, B560C	VF	-	-	0.55 0.70	٧	I <sub>F</sub> = 5.0A, T <sub>A</sub> = 25°C
Leakage Current (Note 3)	20000, 20000	I <sub>R</sub>	-		0.5 20	mA	@ Rated V <sub>R</sub> , T <sub>A</sub> = 25°C @ Rated V <sub>R</sub> , T <sub>A</sub> = 100°C
Total Capacitance		$C_{T}$	-	-	300	pF	$V_R = 4V$ , $f = 1MHz$

Notes:

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/quality/lead\_free.html.
- 2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
- 3. Thermal Resistance: Junction to ambient, unit mounted on PC board with 8.0 mm2 (0.033 mm thick) copper pads as heat sink.
- 4. Short duration pulse test used to minimize self-heating effect.







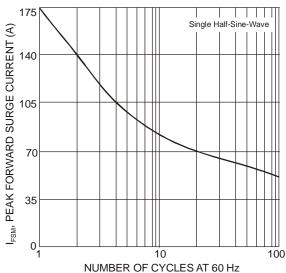
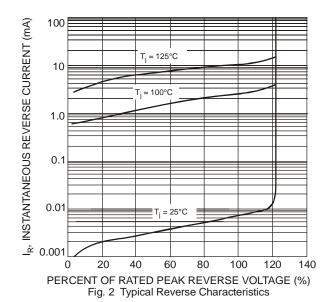
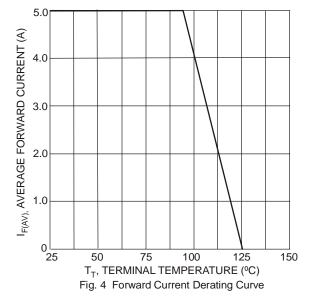


Fig. 5 Max Non-Repetitive Peak Forward Surge Current







## Ordering Information (Note 5)

Part Number	Case	Packaging
B5xxC-13-F	SMC	3000/Tape & Reel

<sup>\*</sup> xx = Device type, e.g. B520C-13-F (SMC package).

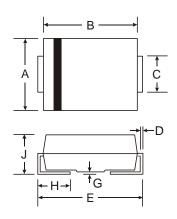
Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**



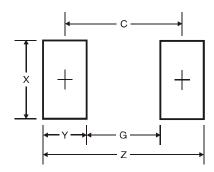
B5x0C = Product type marking code, ex: B540C (SMC package)  $\frac{1}{2}$  = Manufacturers' code marking YWW = Date code marking Y = Last digit of year (ex: 2 for 2002) WW = Week code 01 to 52 x = 2,3,4,5 or 6 - i.e., x = 4 for B540C

# **Package Outline Dimensions**



SMC				
Dim	Min	Max		
Α	5.59	6.22		
В	6.60	7.11		
C	2.75	3.18		
D	0.15	0.31		
Е	7.75	8.13		
G	0.10	0.20		
H	0.76	1.52		
7	2.00	2.62		
All Dimensions in mm				

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	9.3
G	4.4
Х	3.3
Y	2.5
С	6.8



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